

# LARGE CURRENT/LOW DCR MULTILAYER CHIP BEAD



1.65 x 0.8 x 0.8mm

ACML-0603U

RoHS  
Compliant

## FEATURES:

- Suitable for large current applications, current rating up to 6A
- Nickel barrier terminations provide excellent solder heat resistance
- Suitable for flow and reflow soldering
- Other sizes are available

## APPLICATIONS:

- Video equipment, audio equipment
- Automotive electrical equipment
- Communication equipment
- OA equipment and other

## STANDARD SPECIFICATIONS:

**Operating Temperature**      **Storage Temperature**  
 -55°C to +125°C                      -10°C to +40°C, 70% RH max.

Part Number	Impedance (Ω) ± 25%	Z Test Freq. (MHz)	DCR (mΩ) Max.	Ir (mA) Max.
ACML-0603U-300	30	100	60	1800
ACML-0603U-600	60	100	100	1200
ACML-0603U-101A	100	100	150	1000
ACML-0603U-220	22	100	10	6000
ACML-0603U-700	70	100	20	4000
ACML-0603U-331	330	100	70	1500
ACML-0603U-391	390	100	120	1200
ACML-0603U-471	470	100	120	1200
ACML-0603U-101B	100	100	30	3000
ACML-0603U-181	180	100	50	2000
ACML-0603U-221	220	100	50	2000
ACML-0603U-601	600	100	150	1000

### Test Conditions and equipments

**DCR:** Milliohmmeter-HP4338B or equivalent.

**Z:** RF Impedance /Material Analyzer-HP4291B or equivalent; Fixture: HP16192A;

**Ir:** Electric Power, Electric current meter, Thermometer. Ir is direct electric current as chip surface temperature rose by 20°C against chip initial surface temperature (Ta)

**Test Frequency:** 100MHz, -20dBm or 50mV

Unless specified, test condition should be Temp.=5~35°C, Humidity=45~85%.

## PART NUMBER IDENTIFICATION

ACML-0603U- [ ] - [ ]

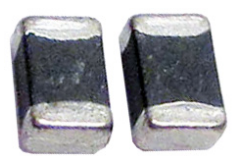
**Impedance Code**  
 Please refer to the Table

**Packaging**  
 T: 4kpcs/reel

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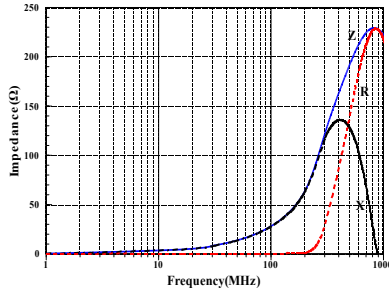
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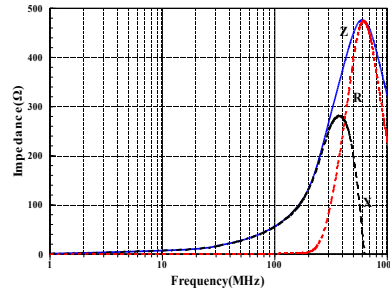
1.65 x 0.8 x 0.8mm

## IMPEDANCE FREQUENCY CHARACTERISTICS

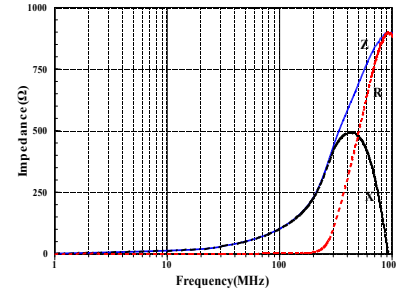
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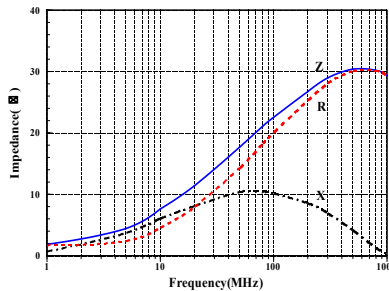
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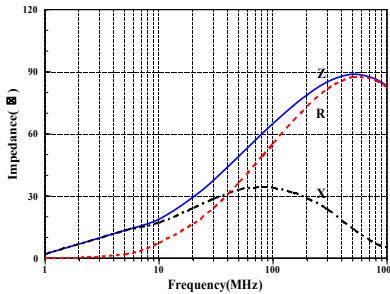
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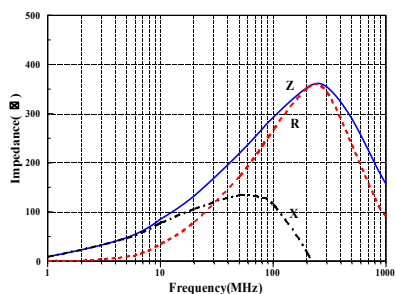
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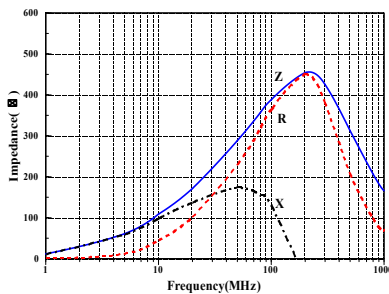
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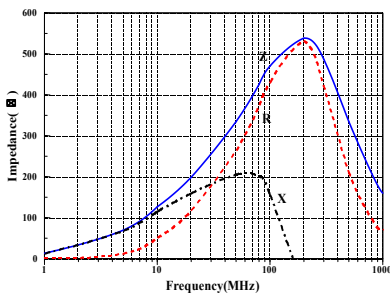
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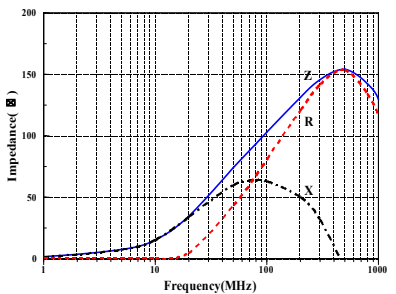
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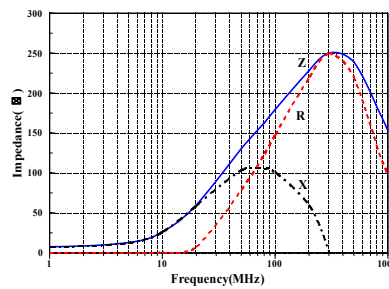
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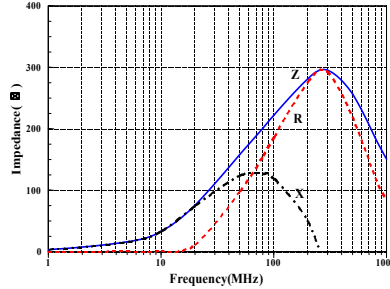
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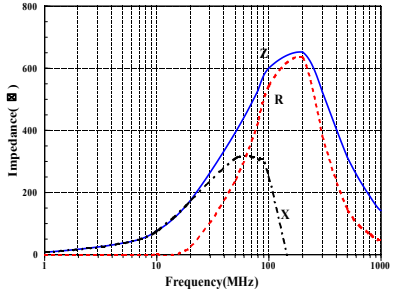
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ACML-0603U-221



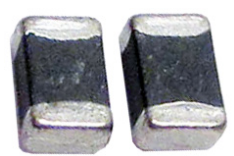
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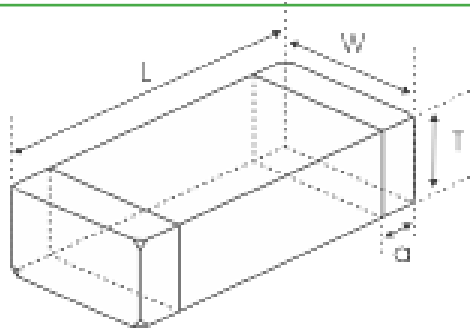
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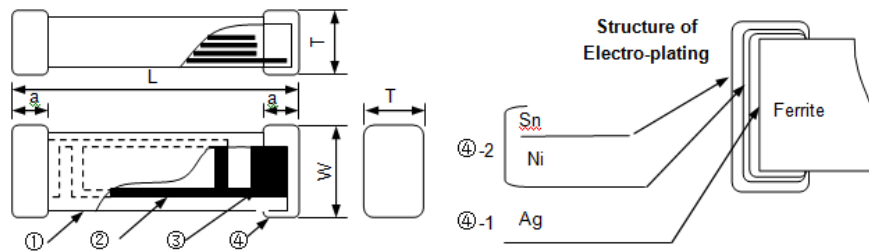
## OUTLINE DIMENSIONS



Series	L	W	T	a
ACML-0603U	1.65±0.15	0.80±0.15	0.80±0.15	0.30±0.20

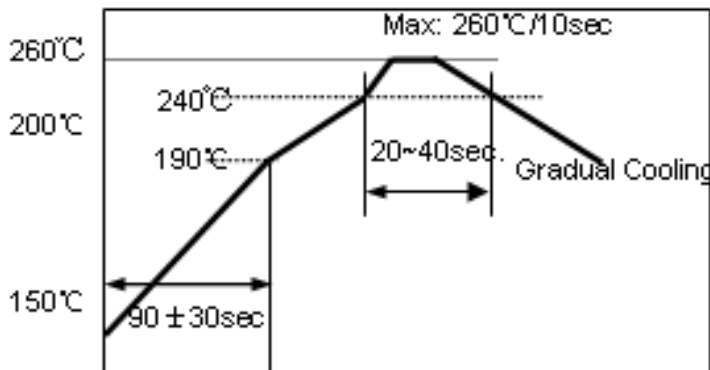
Dimension: mm

## Materials



Code	Part Name	Material Name
①	Ferrite Body	Ferrite Powder
②	Inner Coils	Silver Paste
③	Pull-out Electrode (Ag)	Silver Paste
④-1	Terminal Electrode: Inside Ag	Termination Silver Composition
④-2	Electro-Plating: Ni/Sn plating	Plating Chemicals

## REFLOW PROFILE



- 1~2 °C /sec. Ramp
- Pre-heating: 150~190 °C /90±30 sec.
- Time above 240 °C: 20~40sec
- Peak temperature: 260 °C Max./10sec.
- Solder paste: Sn/3.0Ag/0.5Cu
- Max.2 times for re-flowing